Tessera’s OptiML Wafer-Level Camera Technology Honored by Advanced Packaging Magazine

Groundbreaking Wafer-Level Camera Technology Chosen for Performance and Innovative Design

SAN JOSE, Calif.--(BUSINESS WIRE)--July 17, 2008--Tessera Technologies, Inc. (Nasdaq:TSRA), a leading provider of miniaturization technologies for the electronics industry, today announced that its OptiML™ Wafer-Level Camera (WLC) technology has won Advanced Packaging Magazine’s Novel Package Design award.

The OptiML WLC technology was chosen for its innovative, breakthrough approach to manufacturing optics at the wafer level. Tessera's SHELLCASE® MVP image sensor packaging solution was also an award finalist.

"It is gratifying that Advanced Packaging has recognized our OptiML WLC technology with its Novel Package Design award," said Michael Bereziuk, COO, Tessera. "Tessera had two products as finalists in this category, validating our strategy and reinforcing our reputation for bringing innovative solutions to the market."

According to Gartner Dataquest, the market for cameras in electronic products such as cellular phones, PDAs and security devices, continues to show strength. The industry analyst group projects the camera phone market to reach more than one billion units in 2011.

OptiML WLC technology helps advance the integration of miniaturized cameras in mobile phones, personal computers, security cameras and other electronics. It enables cameras to be manufactured at the wafer level. This reduces camera module size by up to 50 percent over conventional modules used in today's camera phones, while lowering total cost.

"We congratulate you as a winner in this prestigious award program," said Gail Flower, editor-in-chief, Advanced Packaging magazine. "Advanced Packaging is proud to continue its tradition of recognizing excellence in this segment of the industry. In recent years, innovations in advanced packaging processes, materials, and equipment have been driving the semiconductor industry forward. Now more than ever, it's important to acknowledge the achievements of these innovators."

A panel of independent industry experts evaluated submissions in 19 categories. Products were judged on innovation, cost-effectiveness, speed/throughput improvements, quality, ease-of-use, maintainability/repair-ability, and environmental responsibility.

The award winners were announced at Semicon West on July 16, 2008, during a ceremony at the St. Regis Hotel in San Francisco. This marks the 5th anniversary of the Advanced Packaging Awards. The complete list of finalists can be found at: www.tessera.com.

About Tessera

Tessera Technologies, Inc. (Nasdaq:TSRA) is a leading provider of miniaturization technologies for the electronics industry. The company provides a broad range of advanced packaging, interconnect, and consumer optics solutions which are widely adopted in high-growth markets including consumer, computing, communications, medical and defense electronics. Tessera's customers include the world's top semiconductor companies such as Intel, Samsung, Texas Instruments, Toshiba, Micron and Infineon. The company's stock is traded on the Nasdaq National Market under the symbol TSRA. Tessera is headquartered in San Jose, California. For information call 1.408.894.0700 or go to www.tessera.com.

Safe Harbor Statement

This press release contains forward-looking statements, which are made pursuant to the safe harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements involve risks and uncertainties that could cause actual results to differ significantly from those projected. Material factors that may cause results to differ from the statements made include delays, setbacks or losses relating to our intellectual property or intellectual property litigations, or any invalidation or limitation of our key patents; fluctuations in our operating results due to the timing of new license agreements and royalties, or due to legal costs; changes in patent laws, regulation or enforcement, or other factors that might affect our ability to protect our intellectual property; the risk of a decline in demand for semiconductor products; failure by the industry to adopt our technologies; competing technologies; the future expiration of our patents; the future expiration
of our license agreements and the cessation of related royalty income; the failure or refusal of licensees to pay royalties; failure to achieve the growth prospects and synergies expected from acquisition transactions; and delays and challenges associated with integrating acquired companies with our existing businesses. You are cautioned not to place undue reliance on the forward-looking statements, which speak only as of the date of this release. Tessera's filings with the Securities and Exchange Commission, including its Annual Report on Form 10-K for the year ended December 31, 2007 and its Quarterly Report on Form 10-Q for the quarter ended March 31, 2008 include more information about factors that could affect the company's financial results.

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